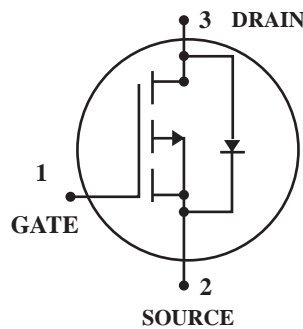


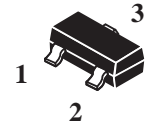
P-Channel Enhancement Mode Power MOSFET

 Lead(Pb)-Free



DRAIN CURRENT
-4.2 AMPERES

DRAIN SOURCE VOLTAGE
-30 VOLTAGE



SOT-23

Features:

- *Advanced trench process technology
- *High Density Cell Design For Ultra Low On-Resistance

Maximum Ratings ($T_A=25^\circ\text{C}$ Unless Otherwise Specified)

Rating	Symbol	Value	Unit	
Drain-Source Voltage	V_{DS}	-30	V	
Gate-Source Voltage	V_{GS}	± 12		
Continuous Drain Current ¹	I_D	($T_A=25^\circ\text{C}$)	-4.2	A
		($T_A=70^\circ\text{C}$)	-3.5	
Pulsed Drain Current ²	I_{DM}	-30		
Power Dissipation	P_D	($T_A=25^\circ\text{C}$)	1.4	W
		($T_A=70^\circ\text{C}$)	1.0	
Junction and Storage Temperature Range	T_J, T_{stg}	-55 ~ +150	$^\circ\text{C}$	

Thermal Characteristics ($T_A=25^\circ\text{C}$ Unless Otherwise Specified)

Rating	Symbol	Typ	Max	Unit	
Maximum Junction-to-Ambient ¹	$R_{\theta JA}$	$t \leq 10\text{s}$	65	90	$^\circ\text{C/W}$
		Steady-State	85	125	
Maximum Junction-to-Lead ³	$R_{\theta JL}$	43	60	$^\circ\text{C/W}$	

1. The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The value in any given application depends on the user's specific board design. The current rating is based on the $t \leq 10\text{s}$ thermal resistance rating.

2. Repetitive rating, pulse width limited by junction temperature.

3. The $R_{\theta JA}$ is the sum of the thermal impedance from junction to lead $R_{\theta JL}$ and lead to ambient.

Device Marking

WTC3401= A1

Electrical Characteristics ($T_A = 25^\circ\text{C}$ Unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Units
Static					
Drain-Source Breakdown Voltage $I_D = -250\mu\text{A}, V_{GS} = 0\text{V}$	BV_{DSS}	-30			V
Zero Gate Voltage Drain Current $V_{DS} = -24\text{V}, V_{GS} = 0\text{V}$	I_{DSS}			-1	μA
$T_J = 55^\circ\text{C}$				-5	
Gate-Body leakage current $V_{DS} = 0\text{V}, V_{GS} = \pm 12\text{V}$	I_{GSS}			± 100	nA
Gate Threshold Voltage $V_{DS} = V_{GS}, I_D = -250\mu\text{A}$	$V_{GS(th)}$	-0.7	-1	-1.3	V
On state drain current $V_{GS} = -4.5\text{V}, V_{DS} = -5\text{V}$	$I_{D(ON)}$	-25			A
Static Drain-Source On-Resistance $V_{GS} = -10\text{V}, I_D = -4.2\text{A}$ $V_{GS} = -4.5\text{V}, I_D = -4\text{A}$ $V_{GS} = -2.5\text{V}, I_D = -1\text{A}$	$R_{DS(ON)}$			70	m Ω
				80	
				120	
Forward Transconductance $V_{DS} = -5\text{V}, I_D = -5\text{A}$	g_{FS}	7	11		S
Diode Forward Voltage $I_S = -1\text{A}, V_{GS} = 0\text{V}$	V_{SD}		-0.75	-1	V
Maximum Body-Diode Continuous Current	I_S			-2.2	A
Dynamic					
Input Capacitance $V_{GS} = 0\text{V}, V_{DS} = -15\text{V}, f = 1\text{MHz}$	C_{iss}		954		pF
Output Capacitance $V_{GS} = 0\text{V}, V_{DS} = -15\text{V}, f = 1\text{MHz}$	C_{oss}		115		pF
Reverse Transfer Capacitance $V_{GS} = 0\text{V}, V_{DS} = -15\text{V}, f = 1\text{MHz}$	C_{rss}		77		pF
Gate resistance $V_{GS} = 0\text{V}, V_{DS} = 0\text{V}, f = 1\text{MHz}$	R_g		6		Ω
Switching					
Total Gate Charge $V_{GS} = -4.5\text{V}, V_{DS} = -15\text{V}, I_D = -4\text{A}$	Q_g		9.4		nC
Gate Source Charge $V_{GS} = -4.5\text{V}, V_{DS} = -15\text{V}, I_D = -4\text{A}$	Q_{gs}		2		nC
Gate Drain Charge $V_{GS} = -4.5\text{V}, V_{DS} = -15\text{V}, I_D = -4\text{A}$	Q_{gd}		3		nC
Turn-On Delay Time $V_{GS} = -10\text{V}, V_{DS} = -15\text{V}, R_L = 3.6\Omega, R_{GEN} = 6\Omega$	$t_{D(on)}$		6.3		ns
Turn-On Rise Time $V_{GS} = -10\text{V}, V_{DS} = -15\text{V}, R_L = 3.6\Omega, R_{GEN} = 6\Omega$	t_r		3.2		ns
Turn-Off Delay Time $V_{GS} = -10\text{V}, V_{DS} = -15\text{V}, R_L = 3.6\Omega, R_{GEN} = 6\Omega$	$t_{D(off)}$		38.2		ns
Turn-Off Fall Time $V_{GS} = -10\text{V}, V_{DS} = -15\text{V}, R_L = 3.6\Omega, R_{GEN} = 6\Omega$	t_f		12		ns
Body Diode Reverse Recovery Time $I_F = -4\text{A}, dI/dt = 100\text{A}/\mu\text{s}$	t_{rr}		20.2		ns
Body Diode Reverse Recovery Charge $I_F = -4\text{A}, dI/dt = 100\text{A}/\mu\text{s}$	Q_{rr}		11.2		nC

Typical Electrical Characteristics

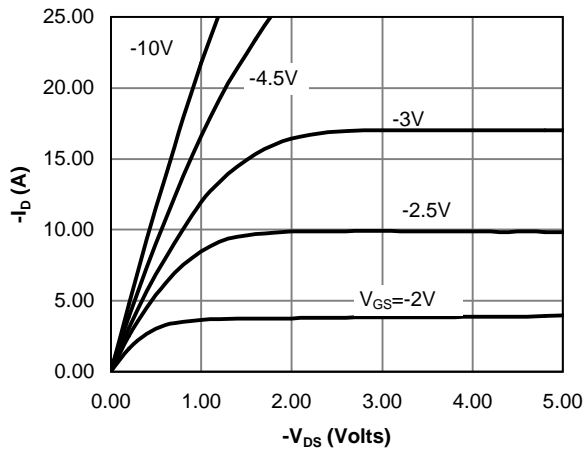


Fig 1: On-Region Characteristics

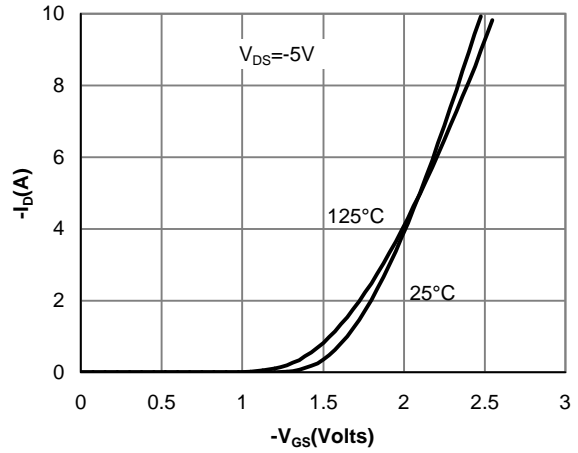


Figure 2: Transfer Characteristics

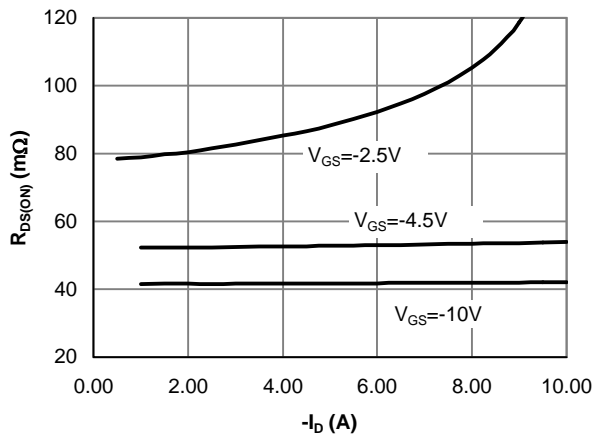


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

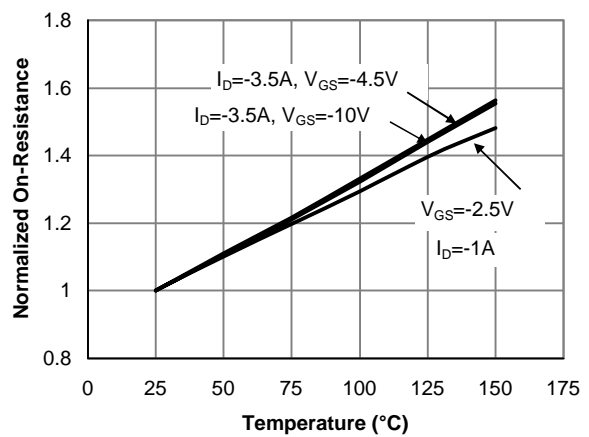


Figure 4: On-Resistance vs. Junction Temperature

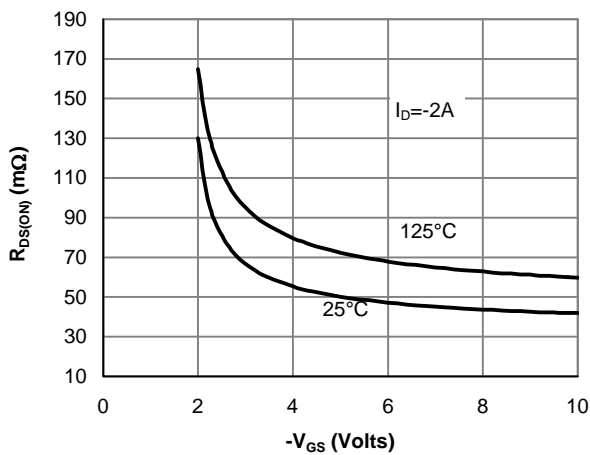


Figure 5: On-Resistance vs. Gate-Source Voltage

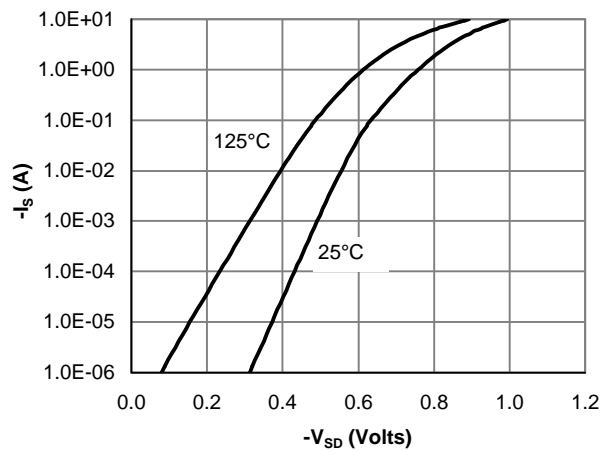


Figure 6: Body-Diode Characteristics

Typical Electrical Characteristics

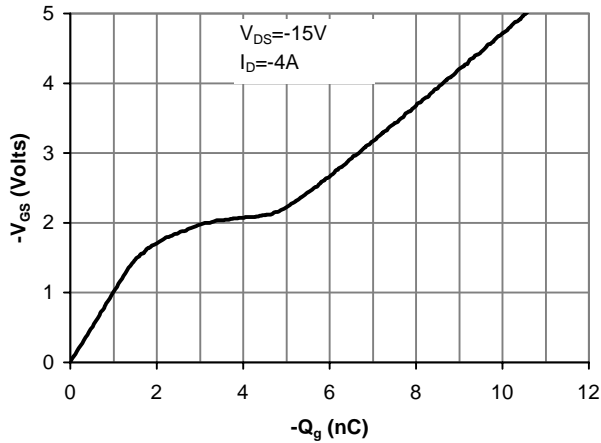


Figure 7: Gate-Charge Characteristics

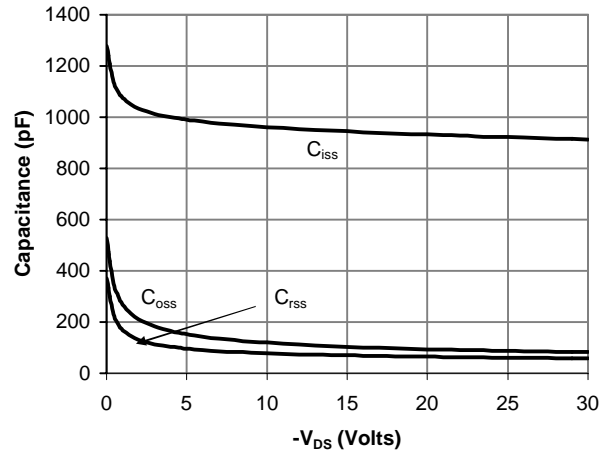


Figure 8: Capacitance Characteristics

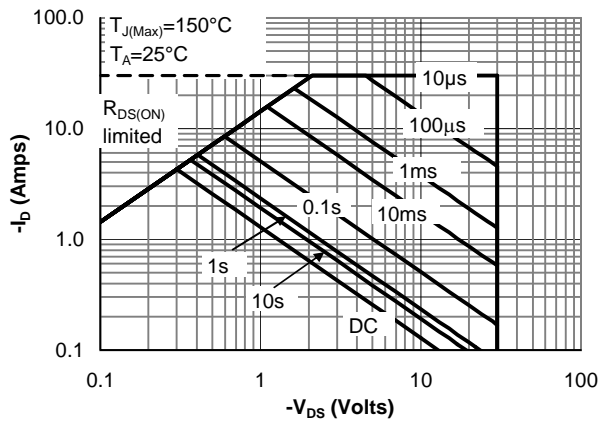


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

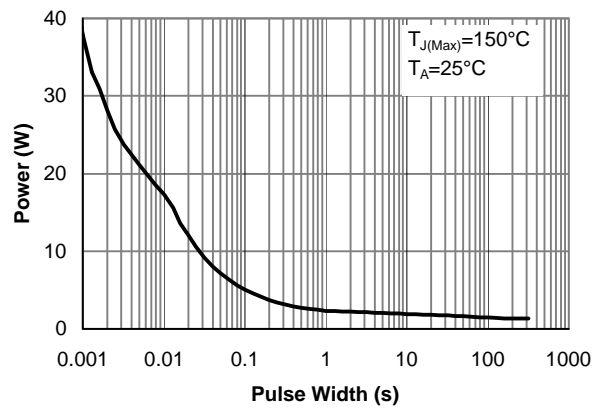


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

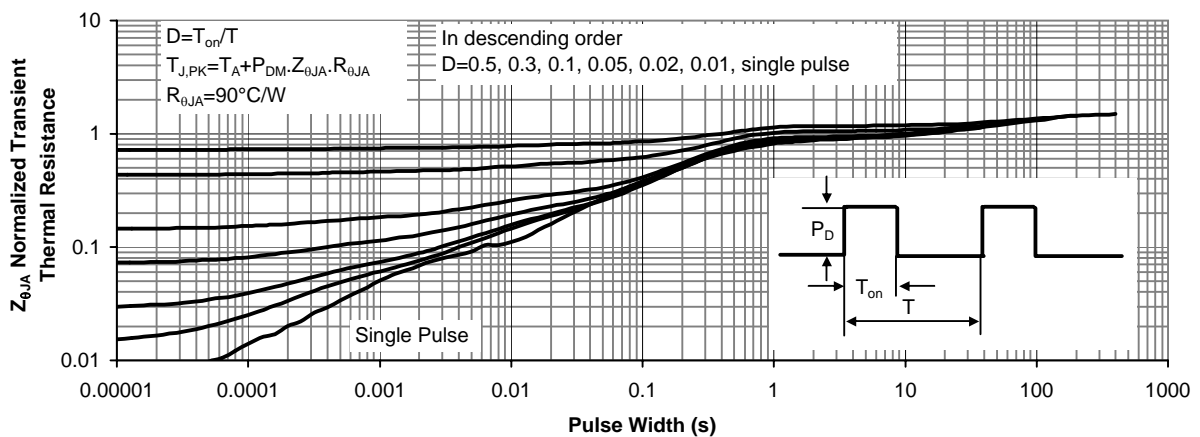
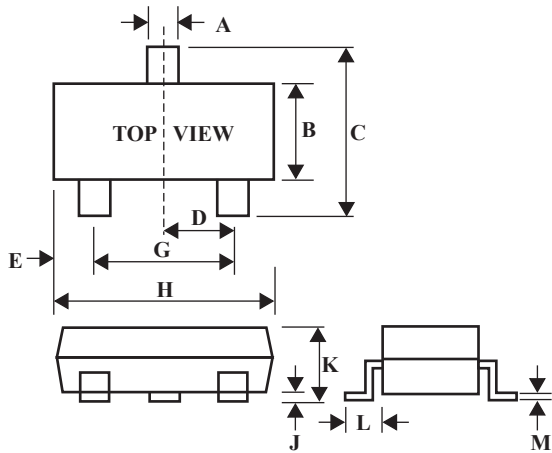


Figure 11: Normalized Maximum Transient Thermal Impedance

SOT-23 Outline Dimension



SOT-23		
Dim	Min	Max
A	0.35	0.51
B	1.19	1.40
C	2.10	3.00
D	0.85	1.05
E	0.46	1.00
G	1.70	2.10
H	2.70	3.10
J	0.01	0.13
K	0.89	1.10
L	0.30	0.61
M	0.076	0.25